ALLPCB

切片检查报告
MICROSECTION INSPECTION

铜厚、焊锡厚阻焊油墨厚 Thickness Measurements of Copper, Solder, Solder Mask (Unit: um)

项目 Items		孔铜 Hole Wall Cu						焊锡厚 Solder Thickness		阻焊油墨 Solder Mask		
		A	B	C	D	E	F	Hole(avg.)	SMT	A	T	L
要求 Requiremet		按资料要求 MI Requirment≥18						≥1-40um		≥10	≥10	≥10
结果 Result	#1								/			
	#2											
	#2											

阻焊 Solder Mask　　样本位置 Specimen Locations　　孔壁的镀铜、焊锡 Hole Wall Cu,Solder

孔粗，介质厚度 Measurements of Drilling Roughness and Dielectric Thickness (Unit: mm)

项目 Item		孔粗 Roughtness	介质厚度 Dielectric Thickness					
要求 Requirement		≤25.4		/	/			
结果 Result	#1			/	/			
	#2							
	#3							

✓ 内在缺陷检查 Defects Inspection

项目 Item	Pass	Fail
钻污 Smear	ACC	
电镀空穴 Plating Void	ACC	
镀层破裂 Plating Crack	ACC	
披锋/瘤粒 Burrs and Nodules	ACC	
露纤维 Glass Fiber Protrusion	ACC	
焊盘浮离 Pad Lifted Land	ACC	
层间分离 Separation Between Layers	ACC	
孔铜剥离 Pull Away of Hole Copper	ACC	
内层连接断裂 Connection Separation Between internal Layer	ACC	
评论Remarks:		

Inspected By 检验员		Date 日期		Approved By 审核		Date 日期	